

Special Issue

Research on Distributed Systems and Cloud Computing

Message from the Guest Editor

Cloud computing is accommodating more diverse resources, as many new computing architectures are produced especially for AI machine learning support. So, distributed cloud technology including edge nodes have emerged. Furthermore, IoT devices and industries' own servers collect data on demand and provide computing power, respectively. Also, hyperscale AI services have been launched, requiring distributed heterogeneous resources for model training and model serving in a cloud computing environment. Therefore, new challenges are emerging to support hyperscale AI services using many different types of cloud continuum, such as edge-to-cloud, cloud-to-cloud (multi-cloud), IoT-to-edge, IoT-to-cloud ones, etc.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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